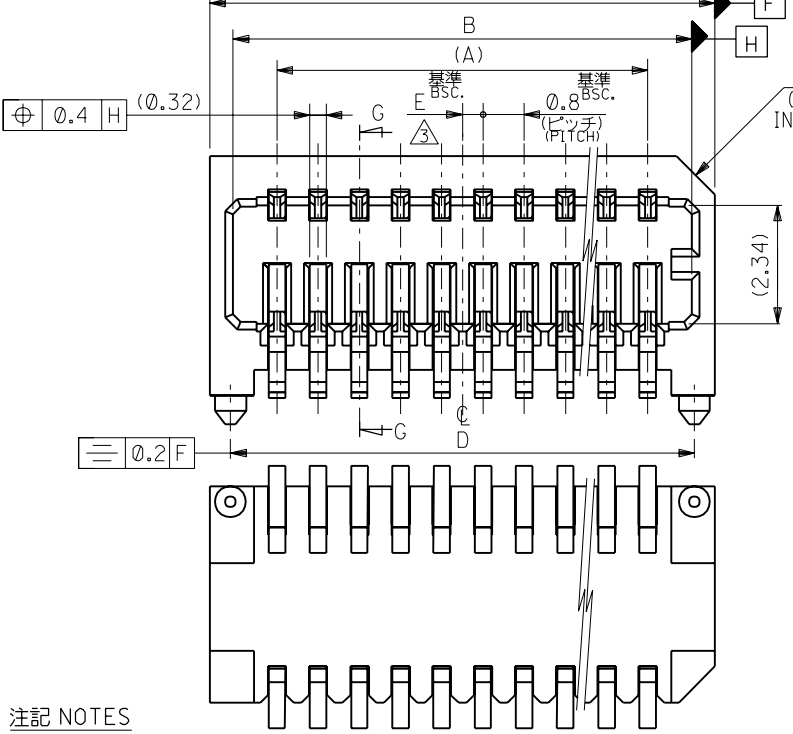
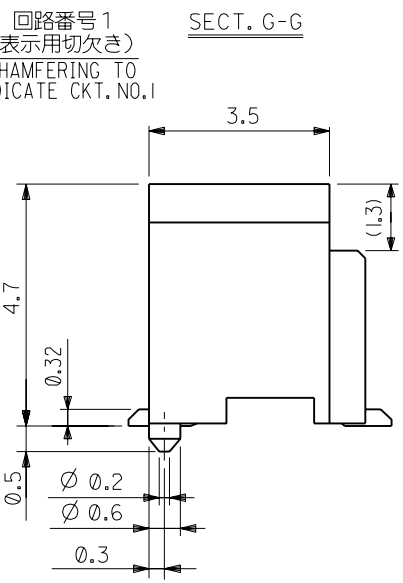
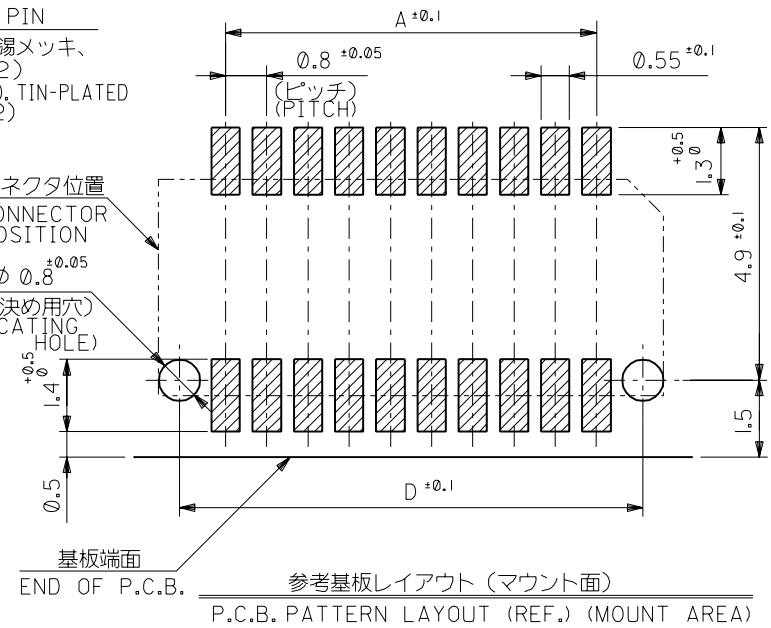
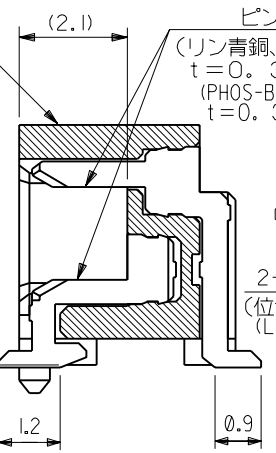
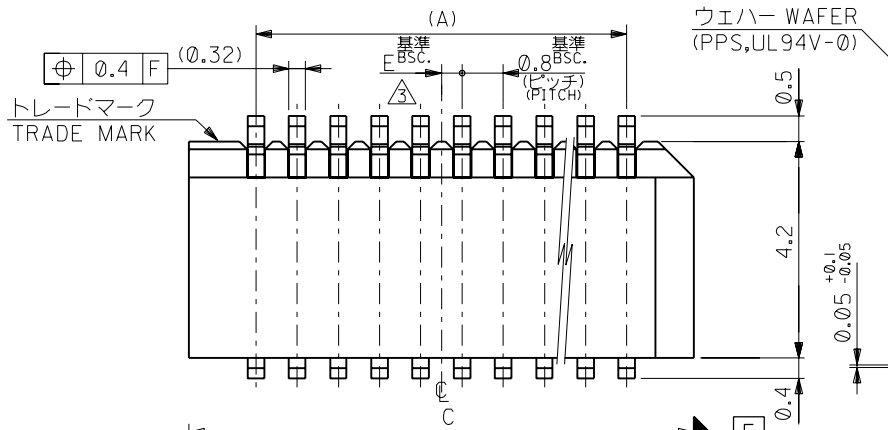


DWG. NO.  
SD-53309-\*\*-17



|     |      |      |      |      |            |         |
|-----|------|------|------|------|------------|---------|
| 0.4 | 17.0 | 17.8 | 16.9 | 15.2 | 53309-4017 | 40      |
| 0.8 | 16.2 | 17.0 | 16.1 | 14.4 | -3817      | 38      |
| 0.4 | 15.4 | 16.2 | 15.3 | 13.6 | -3617      | 36      |
| 0.8 | 14.6 | 15.4 | 14.5 | 12.8 | -3417      | 34      |
| 0.4 | 13.8 | 14.6 | 13.7 | 12.0 | -3217      | 32      |
| 0.8 | 13.0 | 13.8 | 12.9 | 11.2 | -3017      | 30      |
| 0.4 | 12.2 | 13.0 | 12.1 | 10.4 | -2817      | 28      |
| 0.8 | 11.4 | 12.2 | 11.3 | 9.6  | -2617      | 26      |
| 0.4 | 10.6 | 11.4 | 10.5 | 8.8  | -2417      | 24      |
| 0.8 | 9.8  | 10.6 | 9.7  | 8.0  | -2217      | 22      |
| 0.4 | 9.0  | 9.8  | 8.9  | 7.2  | -2017      | 20      |
| 0.8 | 8.2  | 9.0  | 8.1  | 6.4  | -1817      | 18      |
| 0.4 | 7.4  | 8.2  | 7.3  | 5.6  | -1617      | 16      |
| 0.8 | 6.6  | 7.4  | 6.5  | 4.8  | -1417      | 14      |
| 0.4 | 5.8  | 6.6  | 5.7  | 4.0  | -1217      | 12      |
| 0.8 | 5.0  | 5.8  | 4.9  | 3.2  | 53309-1017 | 10      |
| E   | D    | C    | B    | A    | ENG. NO.   | 極数 CKT. |

注記 NOTES

1. 嵌合相手: 52465, 52588 シリーズ  
MATE WITH: 52465, 52588 SERIES
- △ ウェハーの C から隣接するピンの C 迄の位置を示す。  
SHOW POSITION FROM C OF WAFER TO C OF ADJACENT PINS.

|                         |       |        |                        |          |          |
|-------------------------|-------|--------|------------------------|----------|----------|
| 角度 ANGLE                | ±3°   |        |                        |          |          |
| 30 以上 OVER              | +0.3  |        |                        |          |          |
| 10 以上 OVER 30 未満 UNDER  | +0.25 | A      | 変更 REVISION (JC60094)  | M.N.     | '95/8/9  |
| 10 未満 UNDER             | +0.2  | 0      | 新規作成 PROPOSED (J20328) | K.H.T.   | '92/4/15 |
| 一般公差 GENERAL TOLERANCES |       | 記号 LTR | 変更内容 REVISION RECORD   | DR. CHK. | 日付 DATE  |

|                   |                  |
|-------------------|------------------|
| 材料 MATERIAL       | 図中参照 SEE DRAWING |
| 仕上げ FINISH        | — # —            |
| 適用電線範囲 WIRE RANGE | — # —            |
| 被覆外径 INS. RANGE   | — # —            |
| DRAWN BY '92/4/15 | CHK'D BY '95/8/9 |
| K.HAYASHI         | Y.M.HIRAMOTO     |
| APP'D BY '95/8/9  | 尺度 SCALE         |
| M.FUKUSHIMA       | — # —            |

|  |     |
|--|-----|
| MOLEX-JAPAN CO., LTD.<br>日本モレックス株式会社                     |     |
| REVISE ONLY ON CAD SYSTEM                                |     |
| TITLE 名称   |     |
| 0.8 BOARD TO BOARD CONN. WAFER ASS'Y R/A SMT (WITH BOSS) |     |
| DWG. NO. (SHEET 1 OF 2)                                  | REV |
| SD-53309-**-17   | A   |

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

A53309:513

